NSN 8040-01-603-7992

Adhesive - Page 1 of 1

View Online at https://aerobasegroup.com/nsn/8040-01-603-7992

Physical Form:

Paste

Quantity Within Each Unit Package:

10.000 milliliters

Specific Usage Design:

For underfilling chip scale packages (csps) and ball grid arrays (bgas) on circuit boards

Curing Method:

Heat

Features Provided:

Separate catalyst

Special Features:

Premixed and frozen; unfilled; flexible; removable; elevated temperature cure, 5 to 10 minutes at 150 degrees c; must be shipped and stored at minus 40 degrees c or below

Color:

Black

Material:

Plastic epoxy

Supplementary Features:

10 milliliter syringe

Shelf Life:

N/a

Unit Of Measure:

--

Demilitarization:

No

Fiig:

A535p0